

F I G. 3

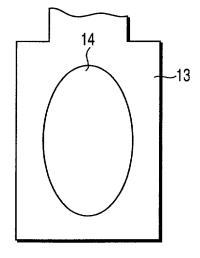


FIG. 4

3/3 Start Form conductive layer (aluminum alloy layer) on piezoelectric substrate 11 and etch it by using predetermined mask pattern to form ∠ST10 comb electrode 12 and connection terminals 13 Arrenge metal bumps 5 on metalized layer 4, which are formed on die attach suface of base 3, at predetermined positions where metal -ST12 bumps are joined to connection terminals 13 of surface acoustis wave element 10 (A or B) Hold/chuck surface acoustic wave element 10 and transfer it to ST14 predetermined element mount area (15A or 15B) on base 3 Press surface of element 10 on which electrode 12 is formed against element mount area (15A or 15B) on base 3 such that ultrasound wave application direction (USa1 or USb1) becomes substantially perpendicular to juxtaposition direction (direction indicated by arrow x) -ST16 of a plurality of surface acoustic wave elements 10 (A or B) and each connection fermianl 13 of element 10 faces arrangement position of metal bump 5 Join or bond connection terminals 13 of element 10 to predetermined portions of metalized layer 4 by pressing surface acoustic wave ∠ST18 element 10 and simultaneously applying ultrasound waves to metal bumps 5 **ST20** ls any surface acoustic wave element to be joined left on metalized layer 4 formed on die attach surface on base 3 NO Fit cap (not shown) on predetermined number of surface acoustic wave elèments 10 (two elements, i.e., elements A and B, in this case) ST22 from above base 3 on which elements are mounted, and join or bond cap to side walls 2 around base 3 End F1G. 5